

# DATA SHEET

## **74LVC04A** Hex inverter

Product specification  
Supersedes data of 2003 Feb 24

2003 Sep 04

**Philips**  
Semiconductors



# **PHILIPS**

## Hex inverter

## 74LVC04A

## FEATURES

- 5 V tolerant inputs for interfacing with 5 V logic
- Wide supply voltage range from 1.2 to 3.6 V
- CMOS low power consumption
- Direct interface with TTL levels
- Inputs accept voltages up to 5.5 V
- Complies with JEDEC standard no. 8-1A
- ESD protection:  
HBM EIA/JESD22-A114-A exceeds 2000 V  
MM EIA/JESD22-A115-A exceeds 200 V.
- Specified from  $-40$  to  $+85$  °C and  $-40$  to  $+125$  °C.

## DESCRIPTION

The 74LVC04A is a high-performance, low-power, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3 or 5 V devices. This feature allows the use of these devices as translators in a mixed 3.3 and 5 V environment.

The 74LVC04A provides six inverting buffers.

## QUICK REFERENCE DATA

GND = 0 V;  $T_{amb} = 25$  °C;  $t_r = t_f \leq 2.5$  ns.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
$t_{PHL}/t_{PLH}$	propagation delay nA to nY	$C_L = 50$ pF; $V_{CC} = 3.3$ V	2.1	ns
$C_i$	input capacitance		4.0	pF
$C_{PD}$	power dissipation capacitance per gate	$V_{CC} = 3.3$ V; notes 1 and 2	15	pF

## Notes

1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

$f_i$  = input frequency in MHz;

$f_o$  = output frequency in MHz;

$C_L$  = output load capacitance in pF;

$V_{CC}$  = supply voltage in Volts;

$N$  = total load switching outputs;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.

2. The condition is  $V_i = \text{GND}$  to  $V_{CC}$ .

## FUNCTION TABLE

See note 1.

INPUT	OUTPUT
nA	nY
L	H
H	L

## Note

1. H = HIGH voltage level;  
L = LOW voltage level.

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## ORDERING INFORMATION

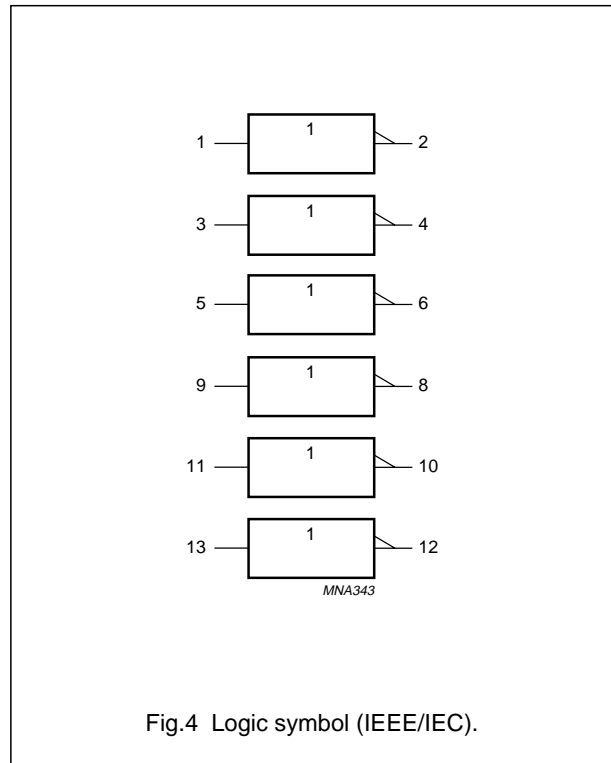
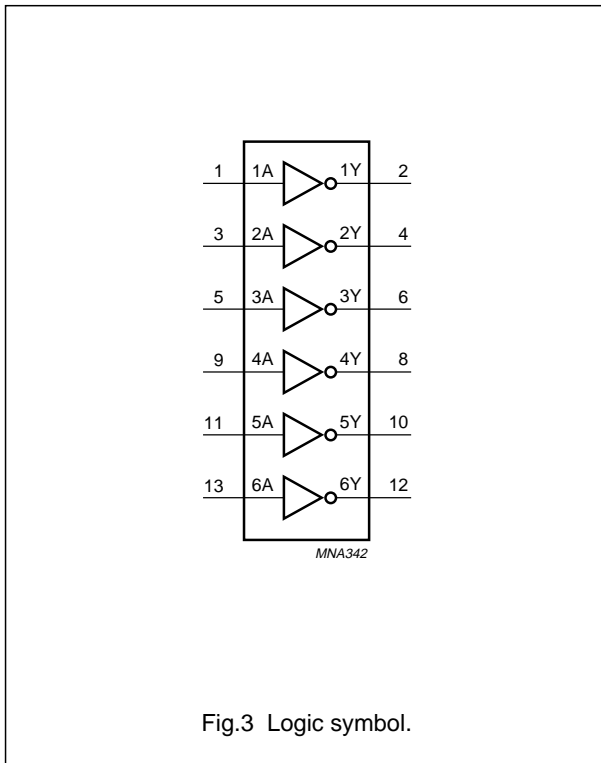
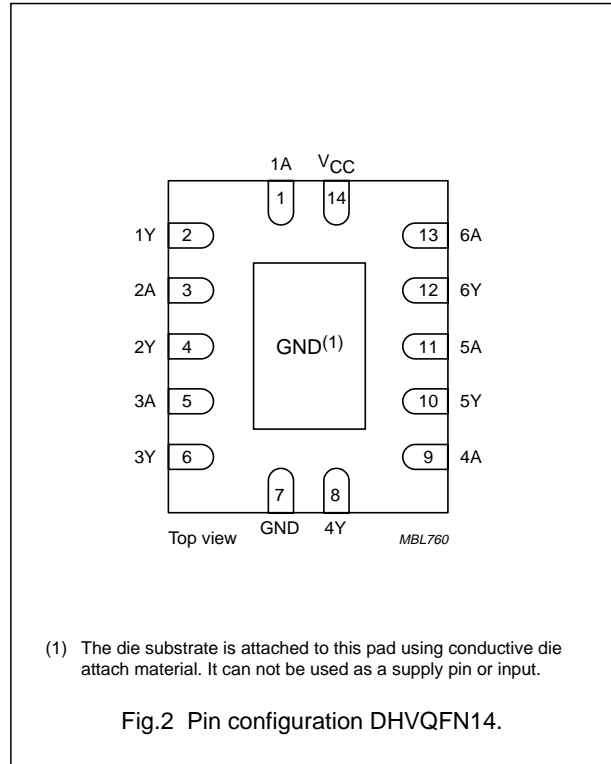
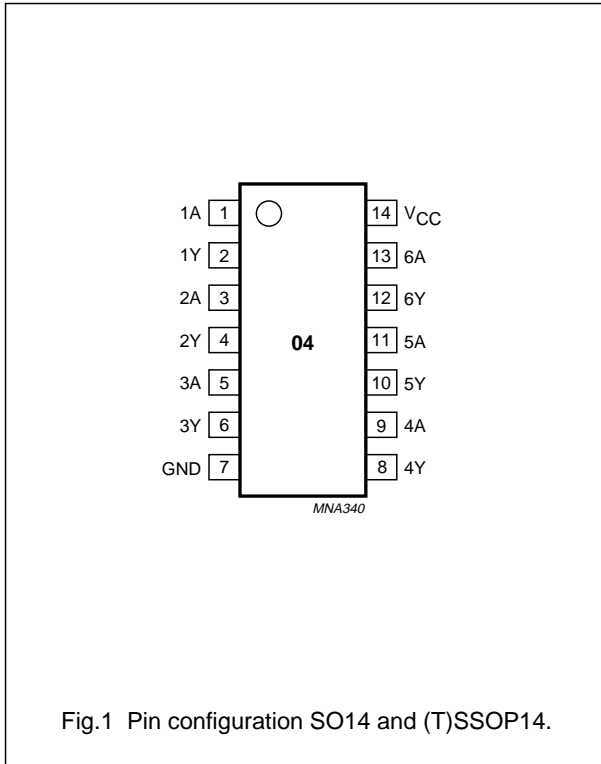
TYPE NUMBER	PACKAGE				
	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE
74LVC04AD	-40 to +125 °C	14	SO14	plastic	SOT108-1
74LVC04ADB	-40 to +125 °C	14	SSOP14	plastic	SOT337-1
74LVC04APW	-40 to +125 °C	14	TSSOP14	plastic	SOT402-1
74LVC04ABQ	-40 to +125 °C	14	DHVQFN14	plastic	SOT762-1

## PINNING

PIN	SYMBOL	DESCRIPTION
1	1A	data input
2	1Y	data output
3	2A	data input
4	2Y	data output
5	3A	data input
6	3Y	data output
7	GND	ground (0 V)
8	4Y	data output
9	4A	data input
10	5Y	data output
11	5A	data input
12	6Y	data output
13	6A	data input
14	V <sub>CC</sub>	supply voltage

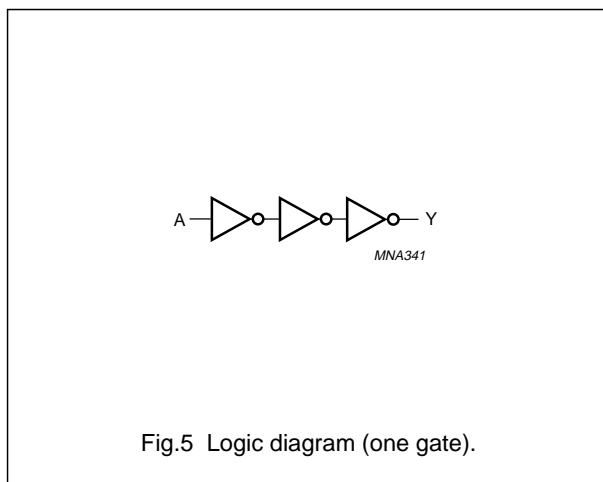
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## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CC}$	supply voltage	for maximum speed performance	2.7	3.6	V
		for low-voltage applications	1.2	3.6	V
$V_I$	input voltage		0	5.5	V
$V_O$	output voltage		0	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+125	°C
$t_r, t_f$	input rise and fall times	$V_{CC} = 1.2$ to $2.7$ V	0	20	ns/V
		$V_{CC} = 2.7$ to $3.6$ V	0	10	ns/V

## LIMITING VALUES

In accordance with the absolute maximum rating system (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CC}$	supply voltage		-0.5	+6.5	V
$I_{IK}$	input diode current	$V_I < 0$	-	-50	mA
$V_I$	input voltage	note 1	-0.5	+6.5	V
$I_{OK}$	output diode current	$V_O > V_{CC}$ or $V_O < 0$	-	$\pm 50$	mA
$V_O$	output voltage	note 1	-0.5	$V_{CC} + 0.5$	V
$I_O$	output source or sink current	$V_O = 0$ to $V_{CC}$	-	$\pm 50$	mA
$I_{CC}, I_{GND}$	$V_{CC}$ or GND current		-	$\pm 100$	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	power dissipation per package	$T_{amb} = -40$ to $+125$ °C; note 2	-	500	mW

## Notes

- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- For SO14 packages: above 70 °C derate linearly with 8 mW/K.  
For SSOP14 and TSSOP14 packages: above 60 °C derate linearly with 5.5 mW/K.  
For DHVQFN14 packages: above 60 °C derate linearly with 4.5 mW/K.

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**DC CHARACTERISTICS**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. <sup>(1)</sup>	MAX.	UNIT
		OTHER	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +85 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		1.2	V <sub>CC</sub>	-	-	V
			2.7 to 3.6	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage		1.2	-	-	GND	V
			2.7 to 3.6	-	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = -100 μA	2.7 to 3.6	V <sub>CC</sub> - 0.2	-	-	V
		I <sub>O</sub> = -12 mA	2.7	V <sub>CC</sub> - 0.5	-	-	V
		I <sub>O</sub> = -18 mA	3.0	V <sub>CC</sub> - 0.6	-	-	V
		I <sub>O</sub> = -24 mA	3.0	V <sub>CC</sub> - 0.8	-	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 100 μA	2.7 to 3.6	-	-	0.2	V
		I <sub>O</sub> = 12 mA	2.7	-	-	0.4	V
		I <sub>O</sub> = 24 mA	3.0	-	-	0.55	V
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND	3.6	-	±0.1	±5	μA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	3.6	-	0.1	10	μA
ΔI <sub>CC</sub>	additional quiescent supply current per input pin	V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0	2.7 to 3.6	-	5	500	μA

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SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. <sup>(1)</sup>	MAX.	UNIT
		OTHER	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +125 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		1.2	V <sub>CC</sub>	–	–	V
			2.7 to 3.6	2.0	–	–	V
V <sub>IL</sub>	LOW-level input voltage		1.2	–	–	GND	V
			2.7 to 3.6	–	–	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>					
		I <sub>O</sub> = -100 μA	2.7 to 3.6	V <sub>CC</sub> - 0.3	–	–	V
		I <sub>O</sub> = -12 mA	2.7	V <sub>CC</sub> - 0.65	–	–	V
		I <sub>O</sub> = -18 mA	3.0	V <sub>CC</sub> - 0.75	–	–	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>					
		I <sub>O</sub> = 100 μA	2.7 to 3.6	–	–	0.3	V
		I <sub>O</sub> = 12 mA	2.7	–	–	0.6	V
		I <sub>O</sub> = 24 mA	3.0	–	–	0.8	V
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND	3.6	–	–	±20	μA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	3.6	–	–	40	μA
ΔI <sub>CC</sub>	additional quiescent supply current per input pin	V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0	2.7 to 3.6	–	–	5000	μA

**Note**

1. All typical values are measured at V<sub>CC</sub> = 3.3 V and T<sub>amb</sub> = 25 °C.

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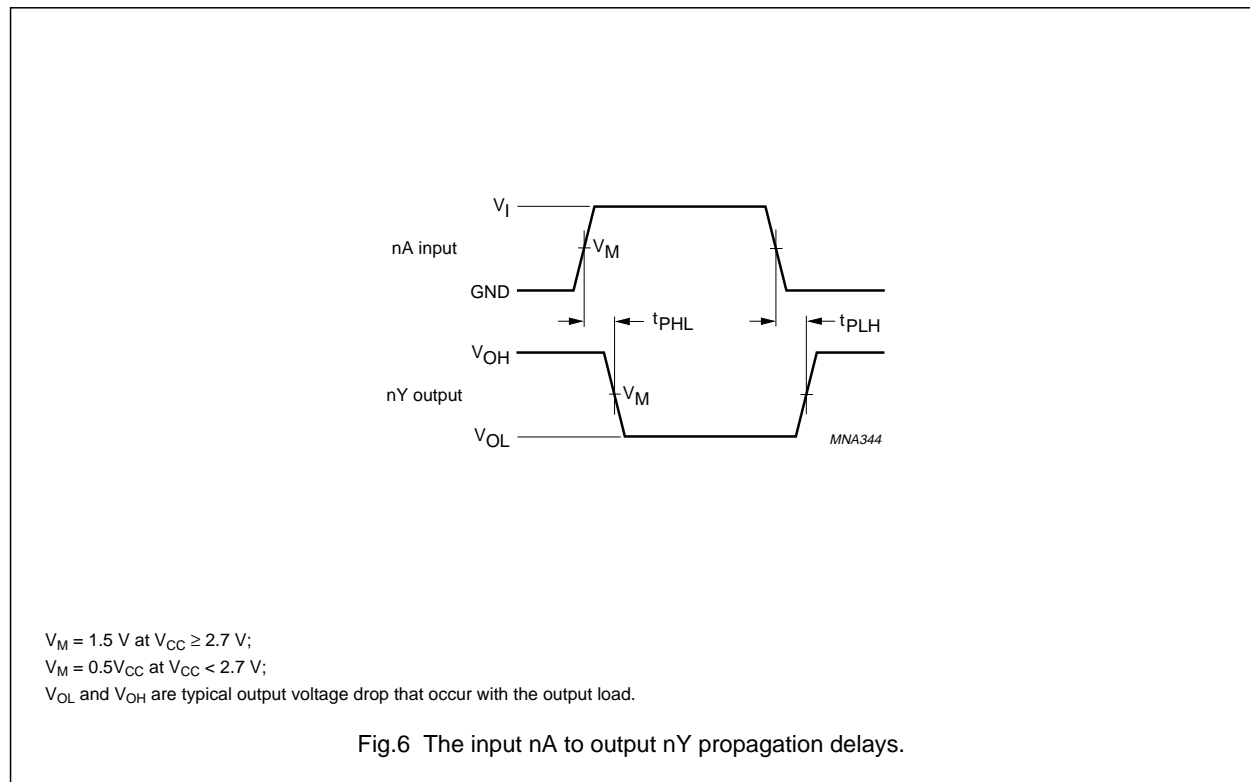
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**AC CHARACTERISTICS**GND = 0 V;  $t_r = t_f \leq 2.5$  ns.

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. <sup>(1)</sup>	MAX.	UNIT
		WAVEFORMS	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +85 °C</b>							
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 6 and 7	1.2	–	14	–	ns
			2.7	1.0	2.2	5.5	ns
			3.0 to 3.6	1.0	1.9	4.5	ns
t <sub>sk(0)</sub>	skew	note 2	3.0 to 3.6	–	–	1.0	ps
<b>T<sub>amb</sub> = -40 to +125 °C</b>							
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 6 and 7	1.2	–	–	–	ns
			2.7	1.0	–	7.0	ns
			3.0 to 3.6	1.0	–	6.0	ns
t <sub>sk(0)</sub>	skew	note 2	3.0 to 3.6	–	–	1.5	ps

**Notes**

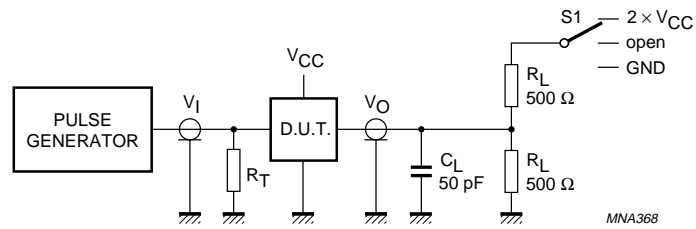
- All typical values are measured at V<sub>CC</sub> = 3.3 V.
- Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

**AC WAVEFORMS**



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$V_{CC}$	$V_I$	$t_{PLH}/t_{PHL}$
1.2 V	$V_{CC}$	open
2.7 V	2.7 V	open
3.0 to 3.6 V	2.7 V	open

Definitions for test circuits:

$R_L$  = Load resistor.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

Fig.7 Load circuitry for switching times.

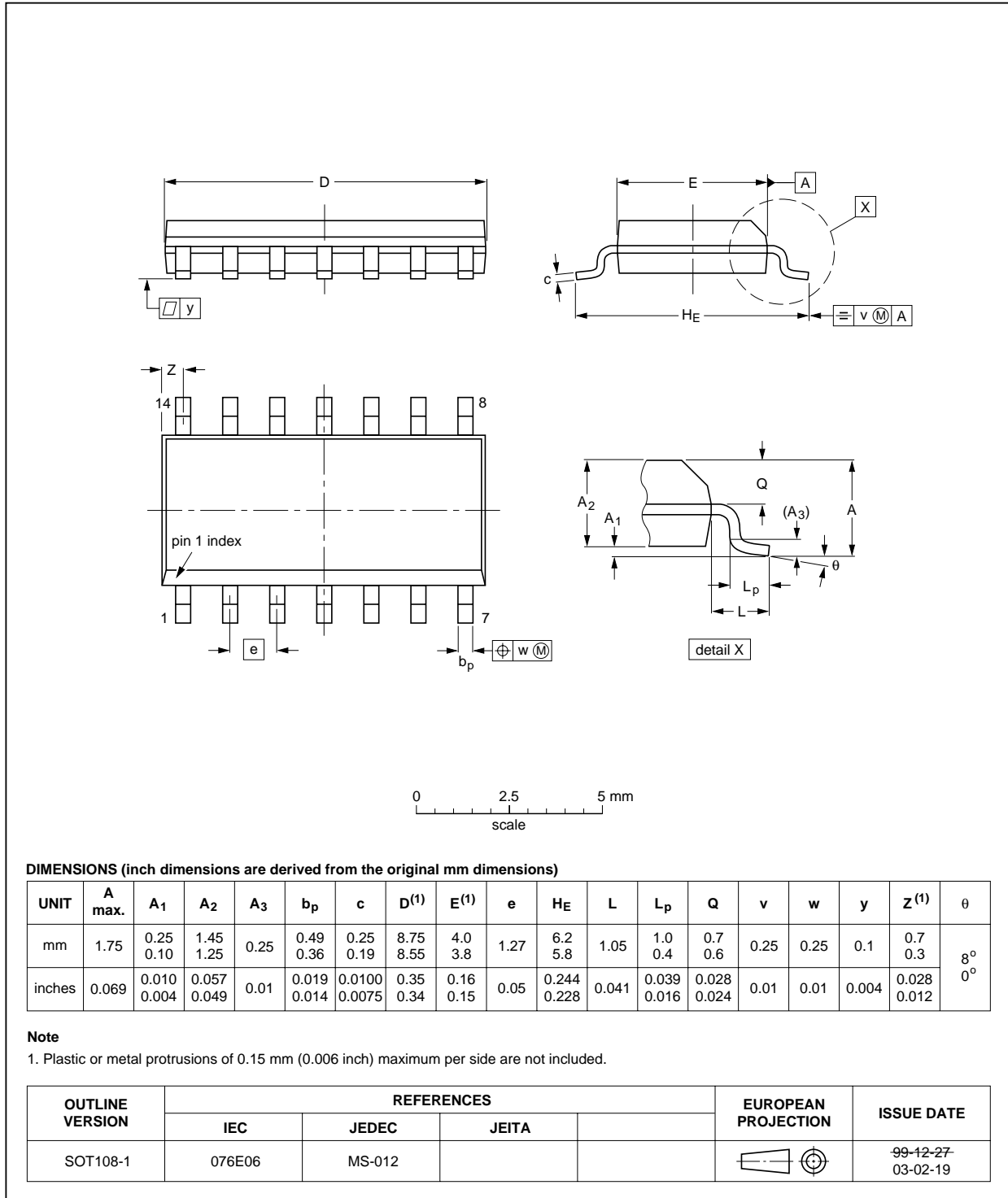
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PACKAGE OUTLINES

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

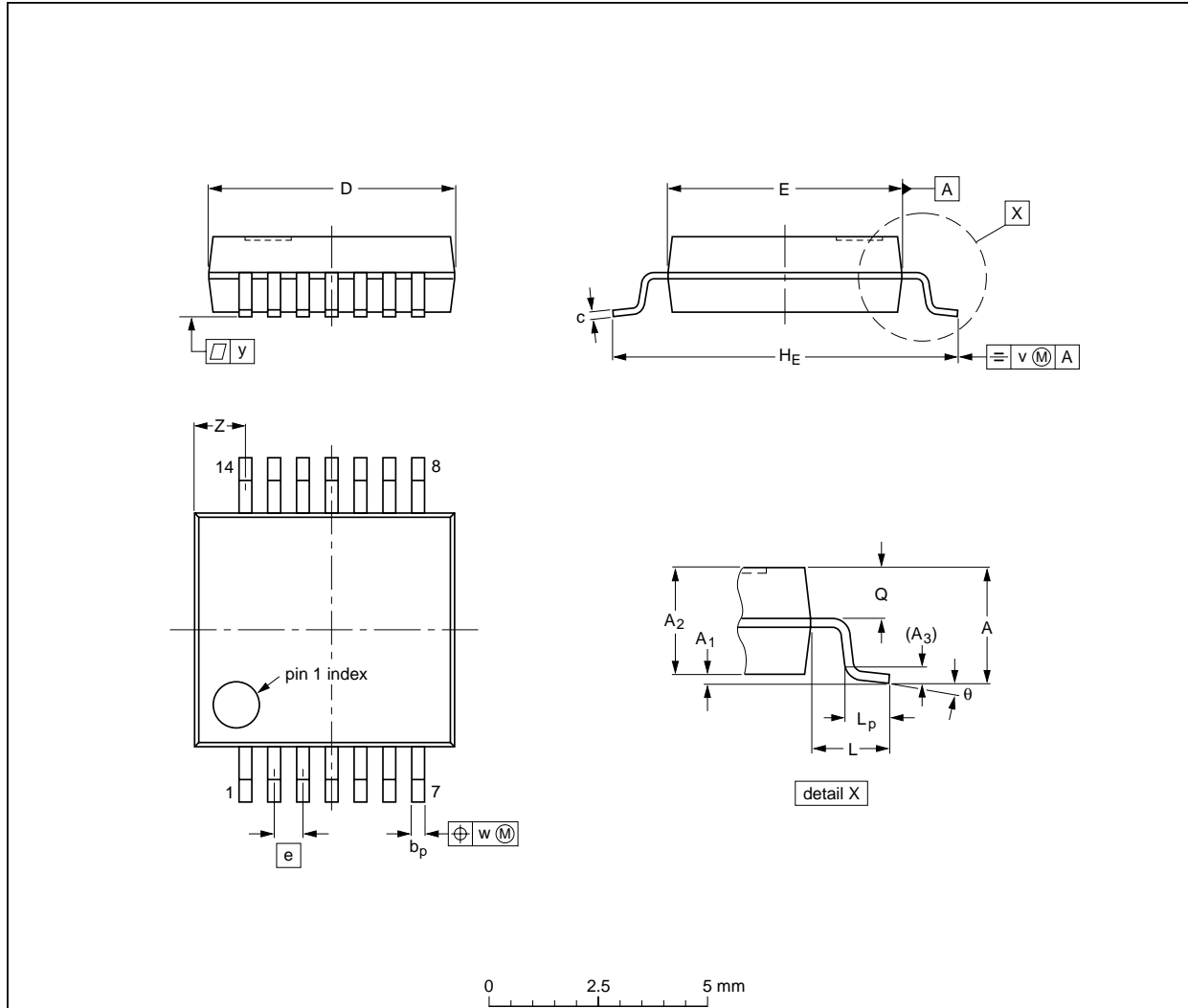


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SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



**DIMENSIONS (mm are the original dimensions)**

UNIT	A <sub>max.</sub>	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

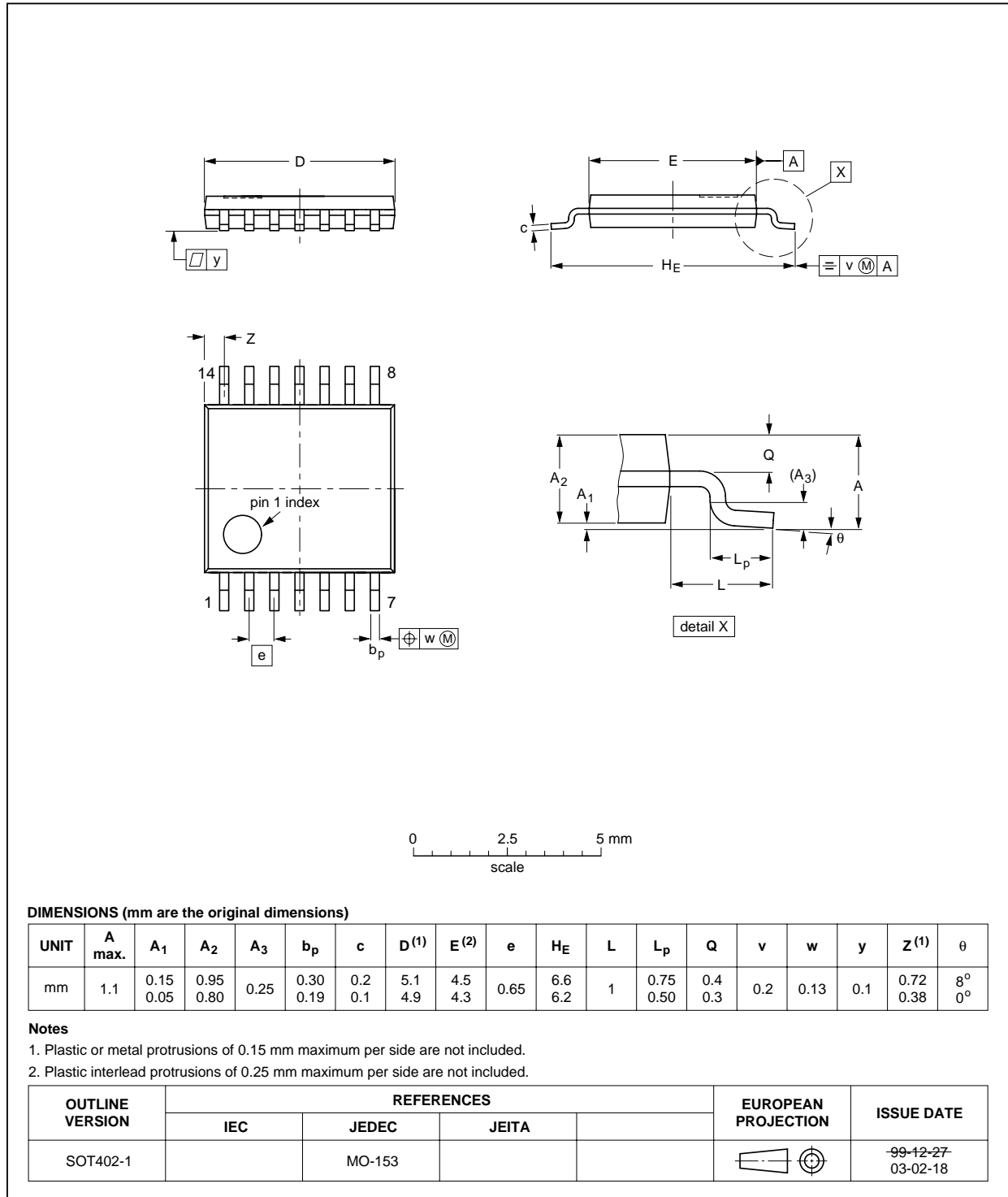
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT337-1		MO-150				99-12-27 03-02-19

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TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

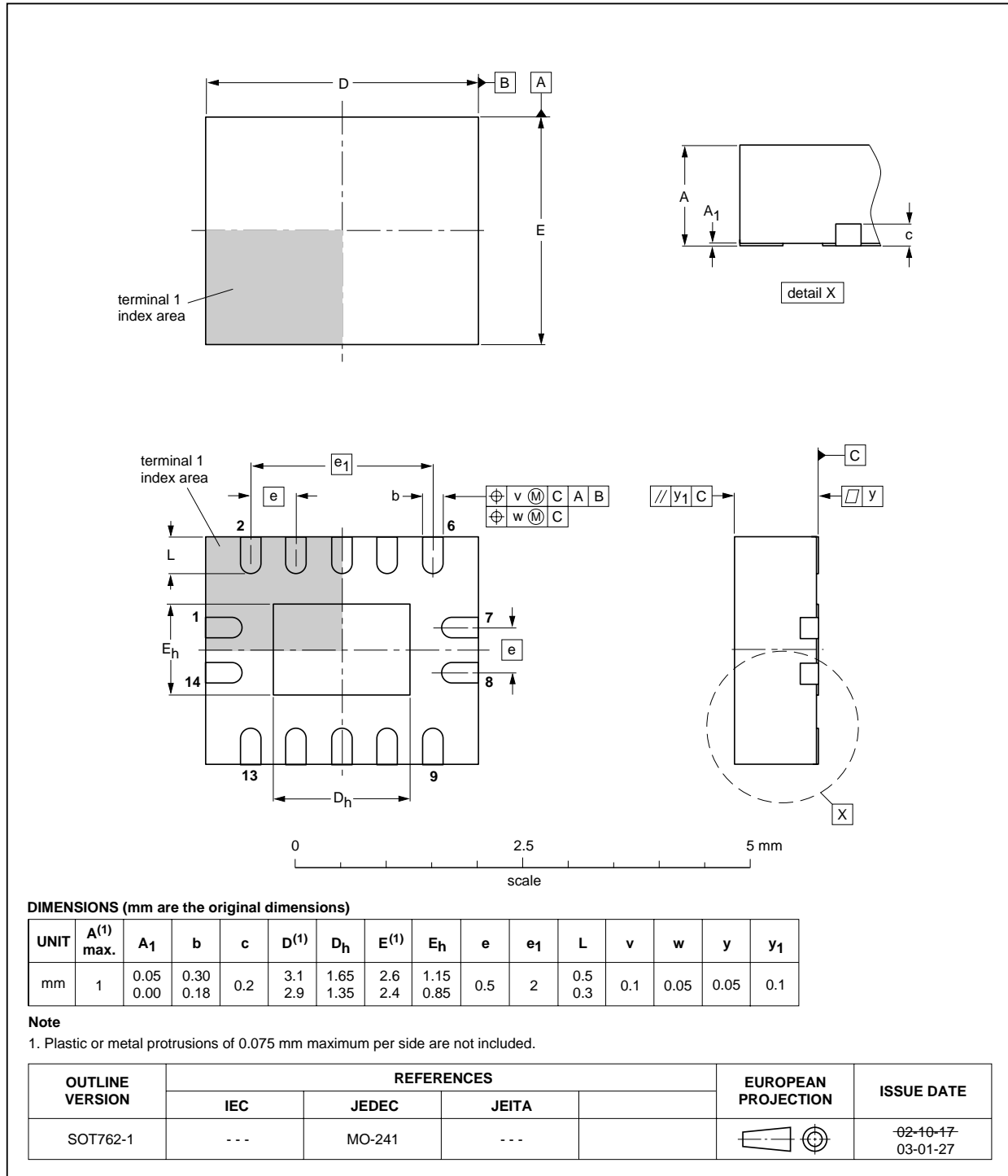


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DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1



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## DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
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